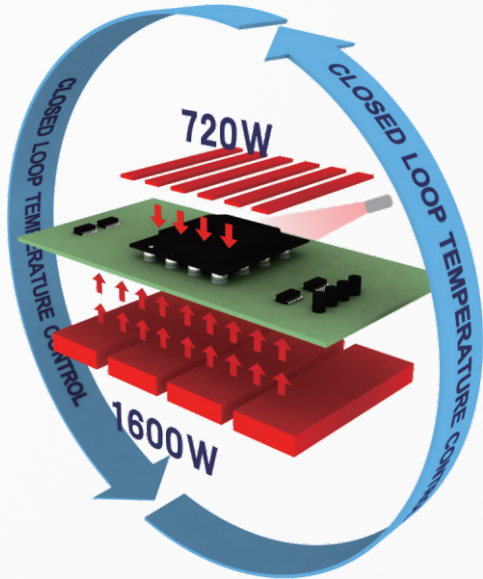


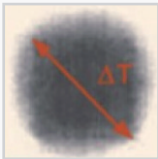
INFRARED BGA REWORK SYSTEM

QUICK EA-H15



Heating Features

Dark infrared heating, non-contact infrared temperature sensor measures surface temperature change of BGA real time, close-loop control, precise temperature process, even heat distribution.



Infrared Heating

Features

- IR part
Infrared temperature sensor detects surface temperature of BGA, close-loop control, even heat distribution.
- PL part
Uses dichromatic vision alignment, make solder ball and pad coincide with each other, easy placement.
- RPC
View solder ball melting process from different sides, help capture reliable process curve.
- Software
Connect with PC, record, control and analyze the whole process, create profiles.
- Control Box
Multifunctional keyboard, easy operation.
- Applications
Laptop motherboard, Mobile motherboard, PAD, IPC board

Specifications

IR Part

General power	2800W(Max)
Voltage	220V AC 50Hz
Power of Bottom Heater	400W×4=1600W(dark infrared heater) 500W×4=2000W(light infrared heating tube optional)
Power of Top Heater	120W×6=720W(infrared heating tube, wave length about 2-8μm)
Top Heating Range	20~60mm(X, Y adjustable)
Bottom Preheating Range	290mm×290mm
Max PCB Size	390mm×420mm
Communication	USB(be connected with PC)
Temperature Sensor	Non-contact infrared sensor
Weight	Around 80Kg
Dimensions	850(L)mm×720(W)mm×730(H)mm

PL Part

Camera	36*12 times magnifying; 24V/300mA; Horizontal resolution 500 lines; PAL format
Prism Size	50mm×50mm
BGA Size Range	2x2mm~60x60mm
Video Output Signal	Video signal

RPC Part

Camera	36*12 times magnifying
	Horizontal resolution 500 lines;PAL format
	LED lighting
Control Box	Multifunctional keyboard
Data Acquisition Card	Quad analog video input
Video Soft	Professional video acquisition software